



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application No. :10/659,090 Confirmation No.:2724
Applicant :Christopher J. Nagel
Filed :September 10, 2003
TC/A.U. :1751
Examiner :Mark T. Kopec
Docket No. :2751.2001 US2
Title: COMPOSITION OF MATTER TAILORING: SYSTEM I

CERTIFICATE OF MAILING OR TRANSMISSION

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DECLARATION UNDER 37 CFR 1.132

Sir:

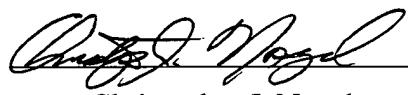
I, Christopher J. Nagel, of 28 Highland Circle, Wayland MA 01778, am the sole inventor of the above identified application.

I am attaching an Excel spreadsheet of the data obtained from the following third party companies of the manufactured copper ingot (14-00-01) presented in the application: GDMS was obtained from SHIVA Technologies of Syracuse, New York; XRF was obtained from the University of Western Ontario, London, Ontario; PIXE was obtained from Elemental Analysis Incorporated, Lexington, Kentucky, and; GDOES was obtained from Twin Analytical of Independence, Ohio. The analysis is consistent with

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Declaration by Christopher J. Nagel

the X-ray fluorescence (XRF) data presented in the application. The third party data confirmed that the manufactured copper ingot contains a different elemental signature that is different from the naturally occurring copper. The unique electronic characteristic of the manufactured copper is not a result from impurities but rather is an intrinsic property of the copper itself.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.



Christopher J. Nagel

Compo. et	date	11/13/2005		10/28/2005		10/24/2005		11/21/2005		1/6/2006		1/6/2006			
		GD049	GD049	GD049	GD049	XRF-UWO	PIXE	GD049	GD049	5 ppm OEM Limit	5 ppm OEM Limit	Copper	Copper		
ppm	sample type	Cu Chop	Confidence Interval	Cu Chop	Copper	Copper	Copper	Copper	Copper	Copper	Copper	14-00-01A	14-00-01R		
	Input	n/a	n/a	Average	Patent	14-00-01	Patent	14-00-01	Patent	14-00-01A	14-00-01R	Patent	Patent		
	workup			99.9999		axial	radial	axial	radial	40-45	Ave 0.05-15	Ave 15-155	40-45	Ave 0.05-15	Ave 15-115
No.															
1	H														
2	He														
3	Li														
4	Be														
5	B	0.0010	#DRV/01												
6	C	-													
7	N	-													
8	O	-													
9	F														
10	Ne														
11	Na														
12	Mg	0.0040	0.0125												
13	Al	0.3938	2.3019												
14	Si	0.0760	0.1689			1350		959.198	1910	50.15	255.8	31.71			126.6
15	P	0.0130	0.0485			8530	5640	1400	6320						
16	S	3.6600	8.3912	24	24										
17	Cl	0.1250	0.2146			112	162	350.719	212.406						
18	Ar														
19	K	0.0300	#DRV/01												
20	Ca														
21	Sc														
22	Ti	0.0114	0.0302					53							
23	V														
24	Cr	0.0340	0.1657												
25	Mn	0.0138	0.0391												
26	Fe	2.1520	4.8122			53		472.395	461.03	62.38	73.99	57.38	53.6	61.79	52.49
27	Co	0.0140	0.0382												
28	Ni	0.5520	1.0635												
29	Cu	Matrix		Matrix	Matrix	891100	893300	761580	862230	995600	993900	995500	996100	993500	995900
30	Zn														
31	Ge														
32	Se														
33	As	0.4760	0.6351												
34	Se	0.6160	0.9602												
35	Br														
36	Kr														
37	Rb														
38	Sr														
39	Y														
40	Zr														
41	Nb														
42	Mo	0.0153	0.0390												
43	Tc														
44	Ru														
45	Rh							372	315						
46	Pd														
47	Ag	8.7800	10.2431												
48	Cd														
49	In	Binders													
50	Sn	0.2900	0.7513												
51	Sb	0.4960	1.1273												
52	Te	0.1340	0.3199												
53	I														
54	Xe														
55	Cs														
56	Ba	0.0035	0.0060												
57	La							105							
58	Ce														
59	Pr														
60	Nd														
61	Pm														
62	Sm														
63	Eu														
64	Gd														
65	Tb														
66	Dy														
67	Ho														
68	Er														
69	Tm							148							
70	Yb														
71	Lu														
72	Hf														
73	Ta														
74	W	0.2183	1.1874												
75	Re							128	155						
76	Os							118	78						
77	Ir														
78	Pt														
79	Au														
80	Hg														
81	Tl														
82	Pb	0.7620	1.9283							91.85	83.3	95.1	109.3	104	109.3
83	Bi	0.1760	0.2922							47.61	115.1	51.53	33.71	148.5	34.63
84	Po														
85	At														
86	Rn														
87	Fr														
88	Rs														
89	Ac														
90	Th														
91	Pa														
92	U														
								99.00%	100.20%	78.475	87.114		200.00		110.30
													N/A		0.2

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